



FIG. 1

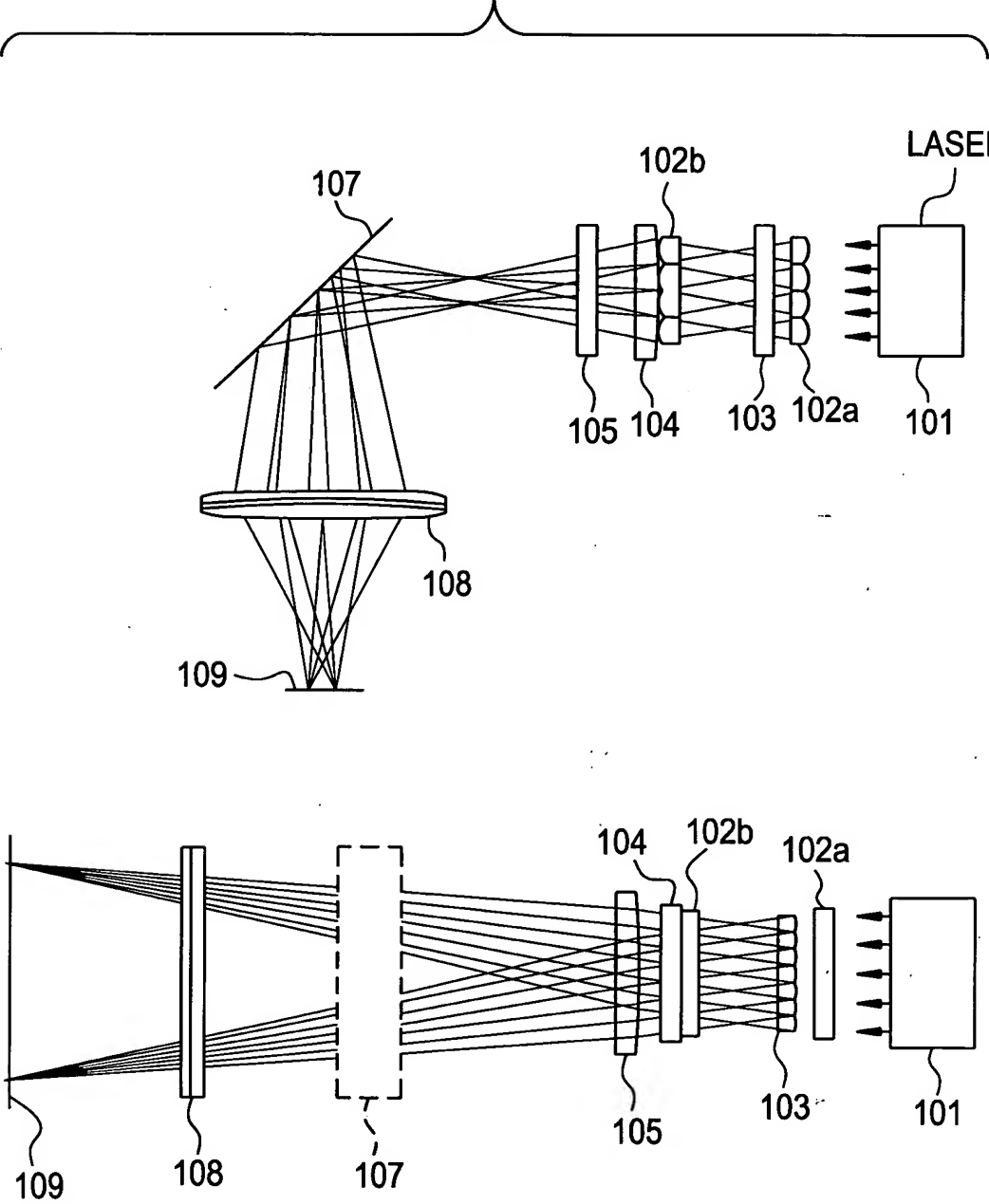


FIG. 2

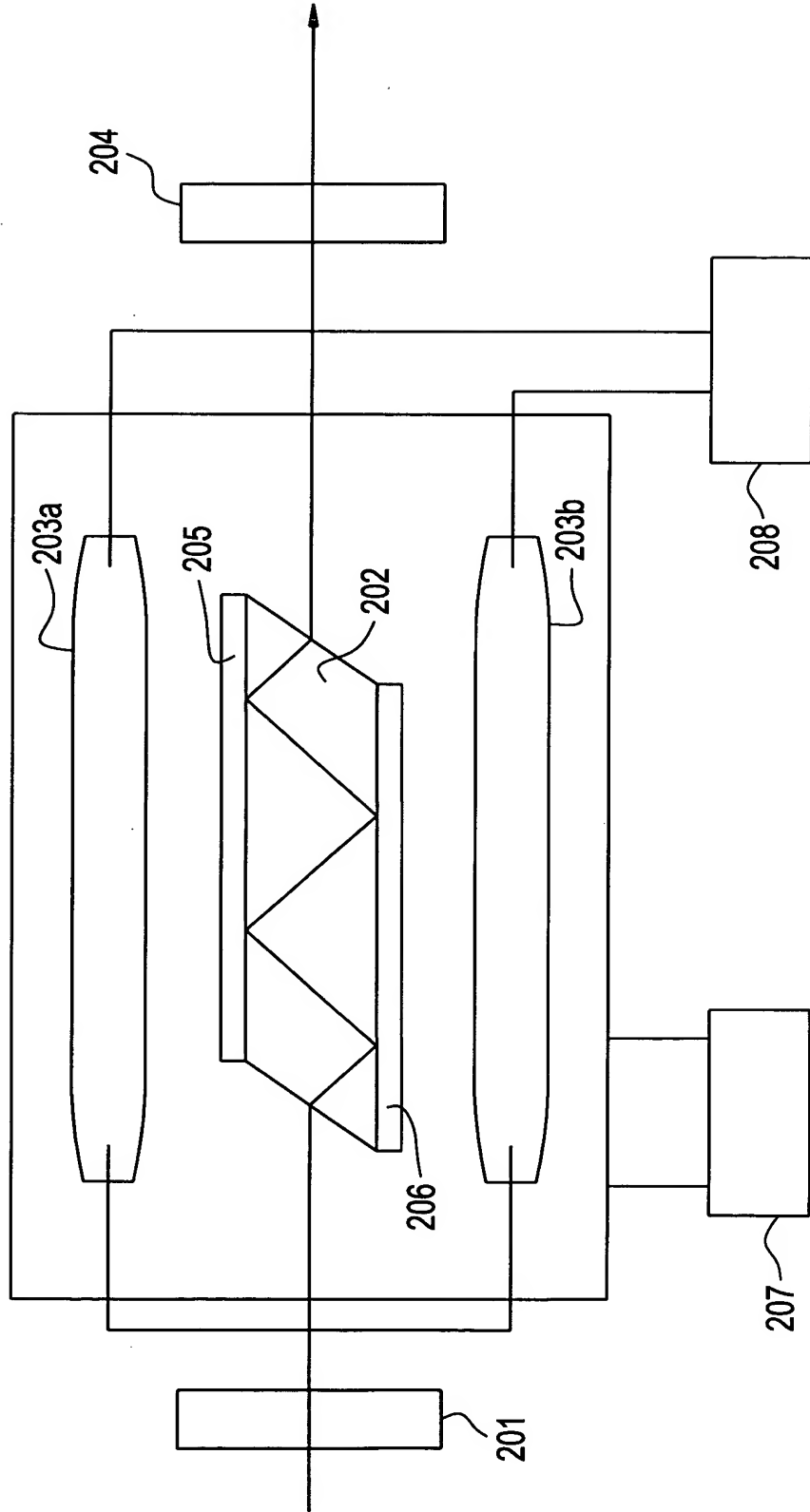


FIG. 3A

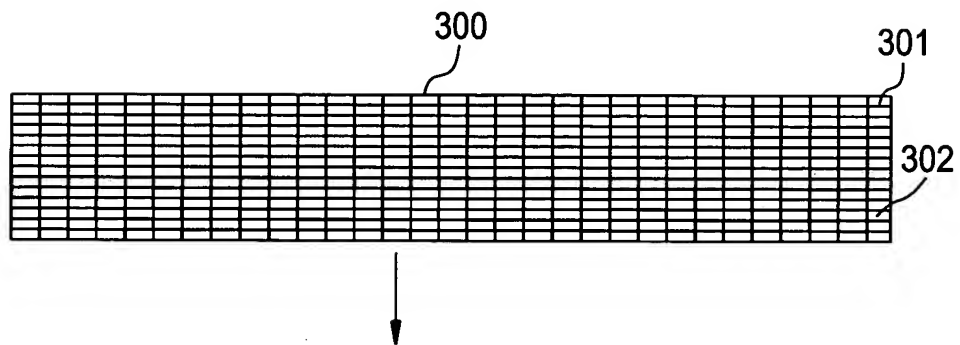


FIG. 3B

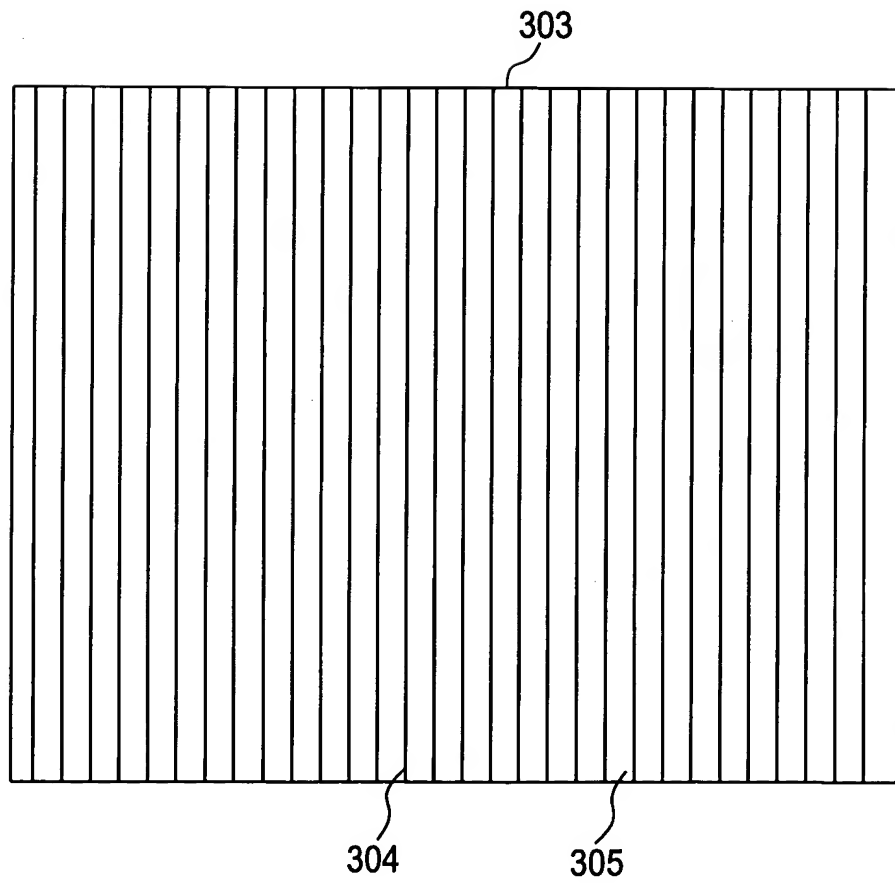


FIG. 4A

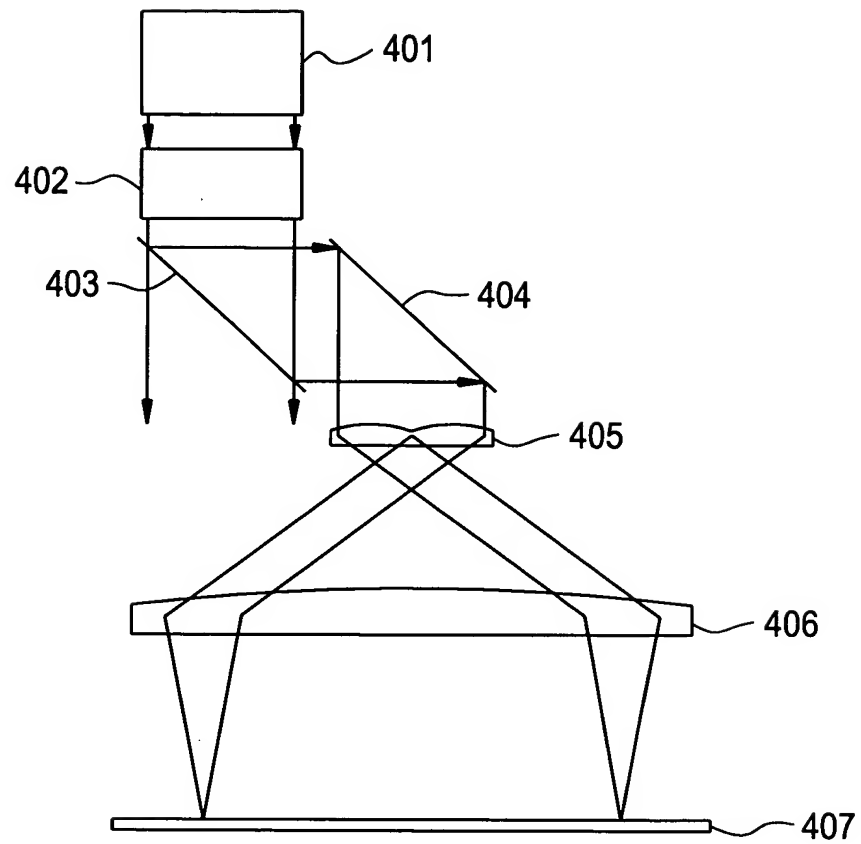


FIG. 4B

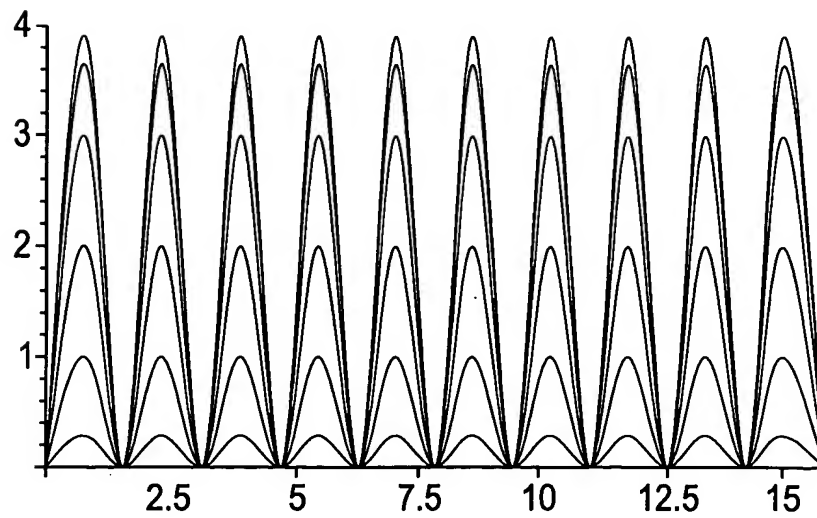


FIG. 5A

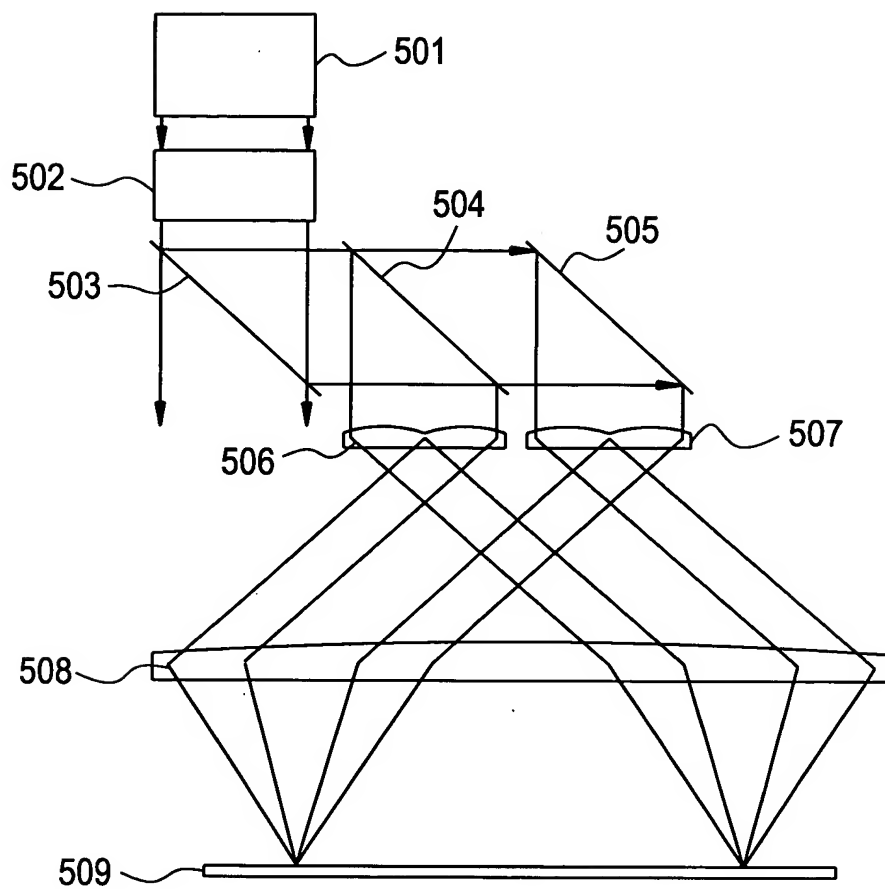


FIG. 5B

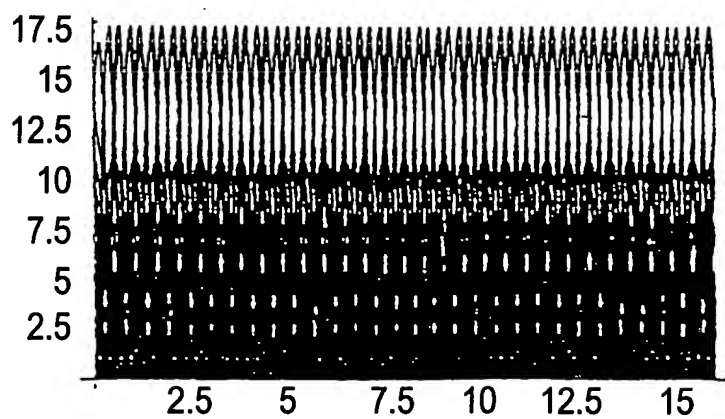


FIG. 6

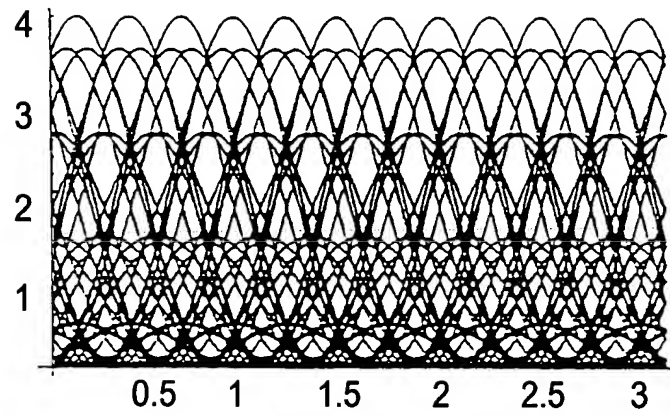


FIG. 7

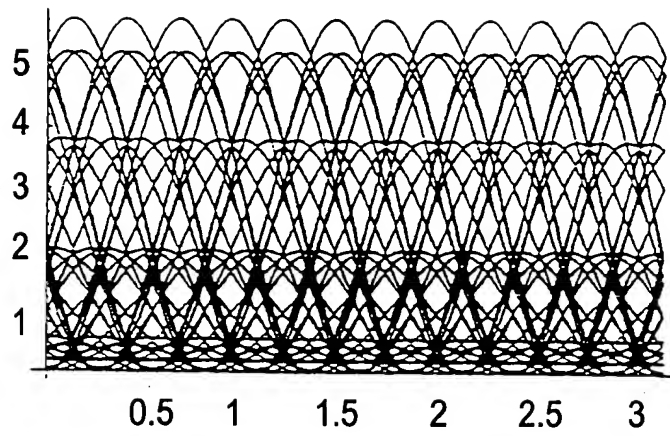


FIG. 8

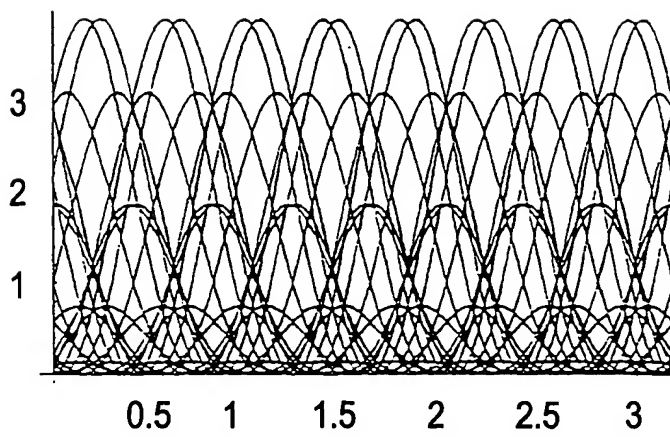


FIG. 9

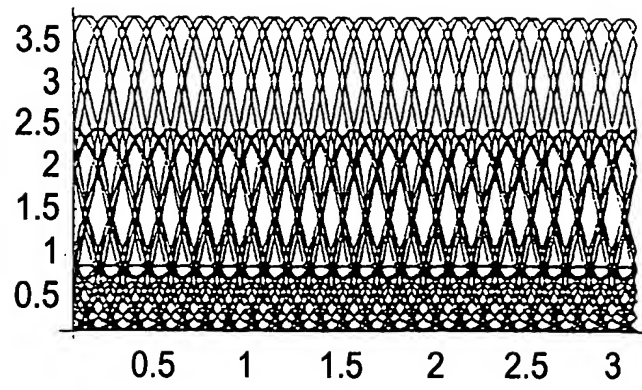


FIG. 10

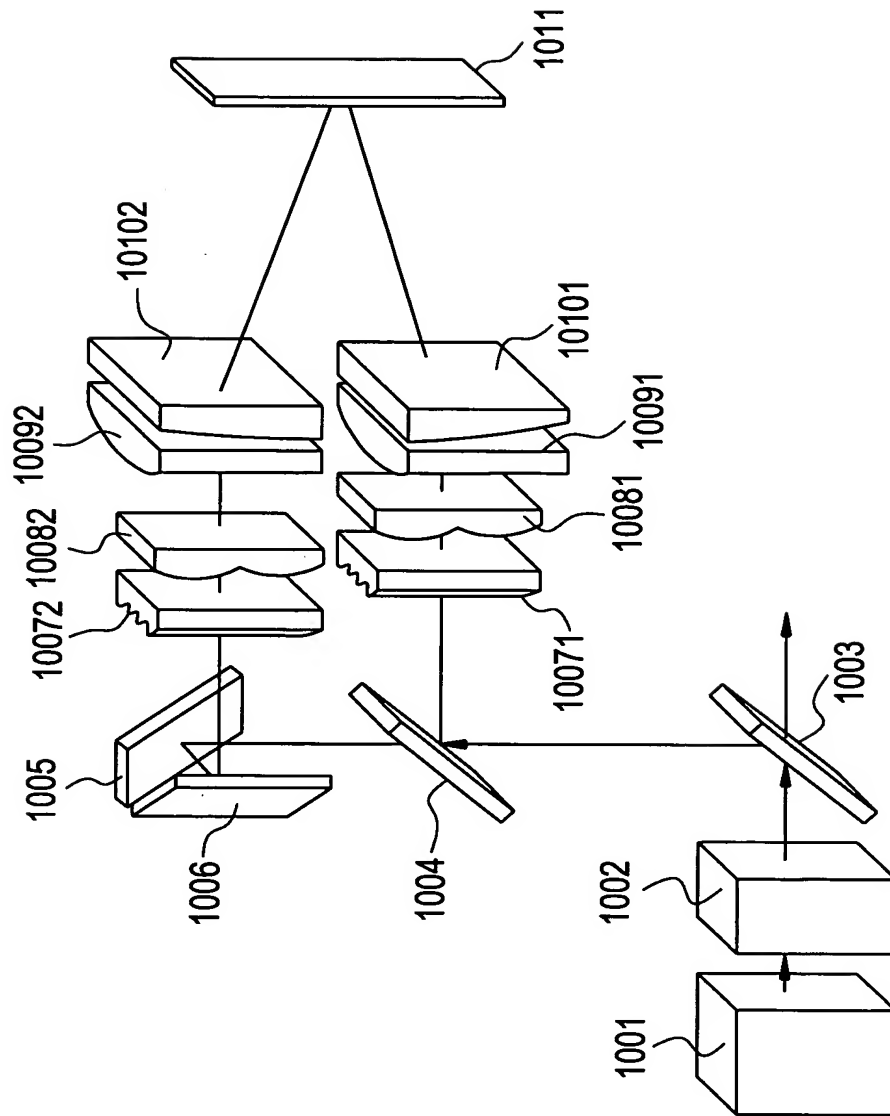
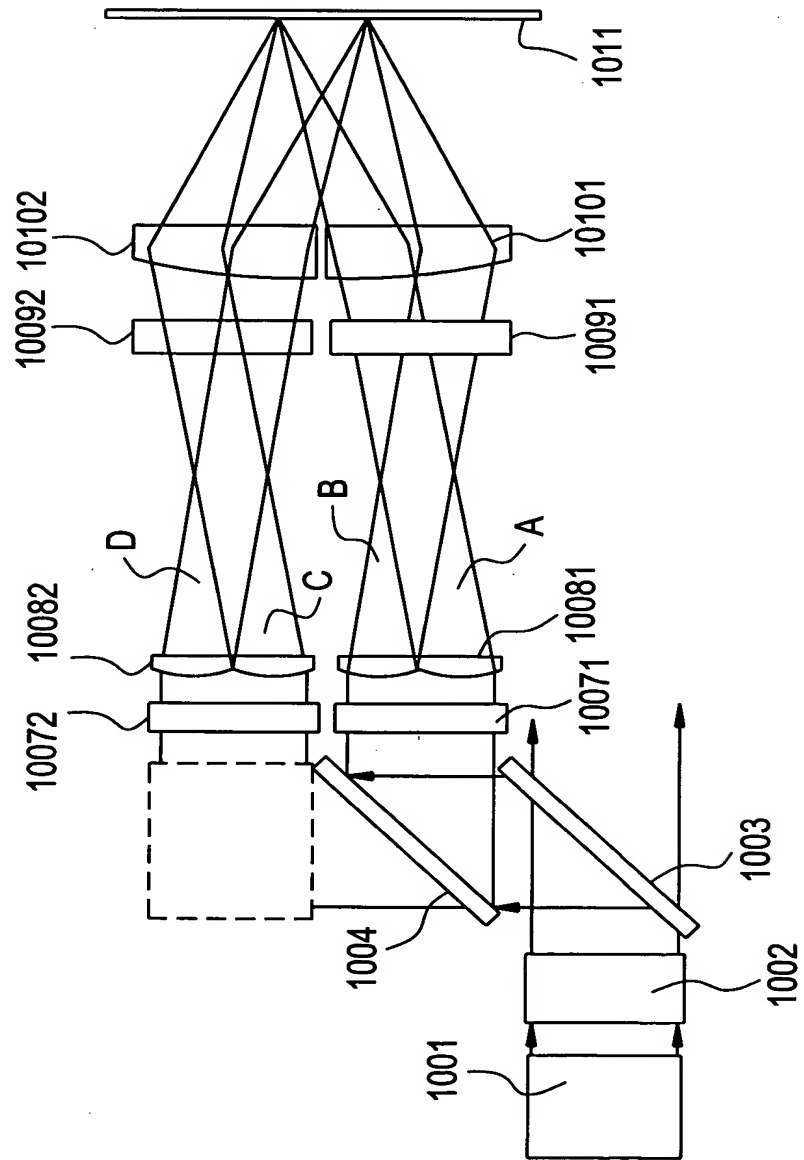
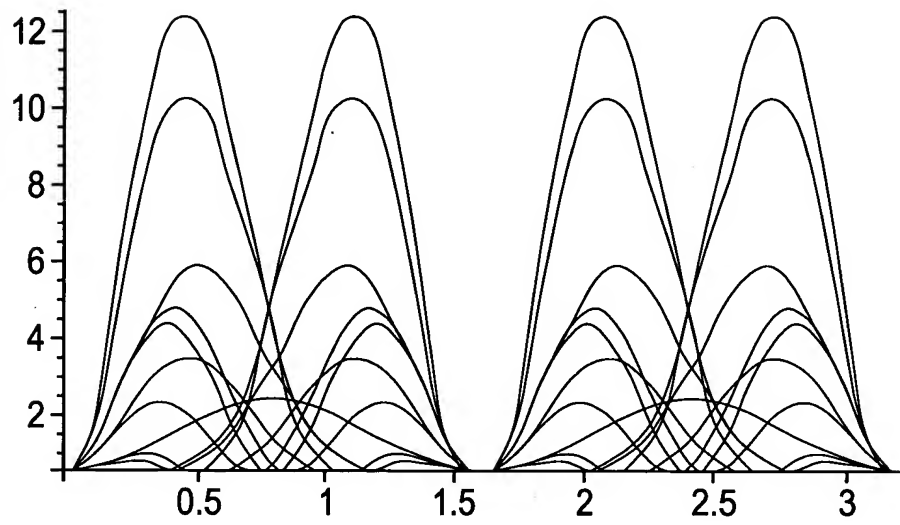




FIG. 11



**FIG. 12A**



**FIG. 12B**

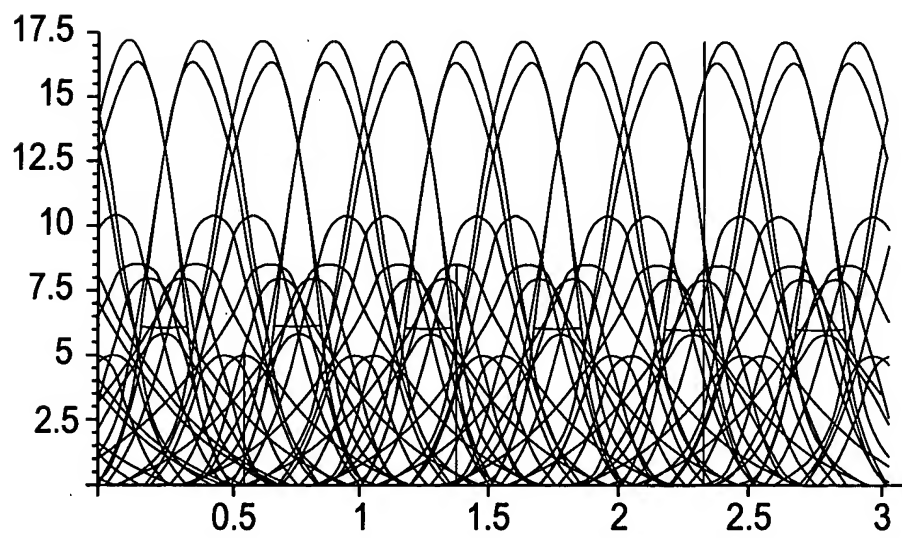


FIG. 13

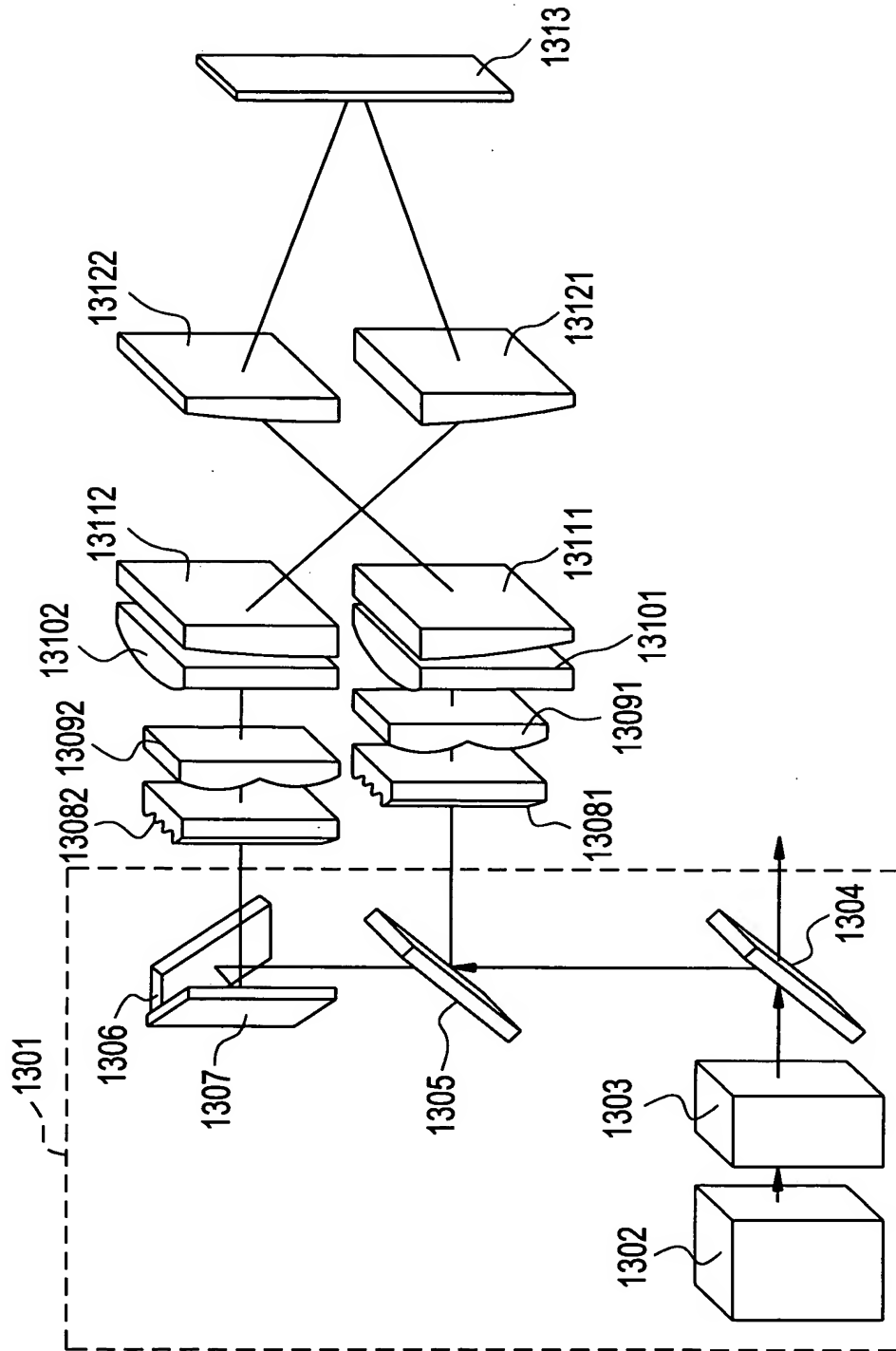
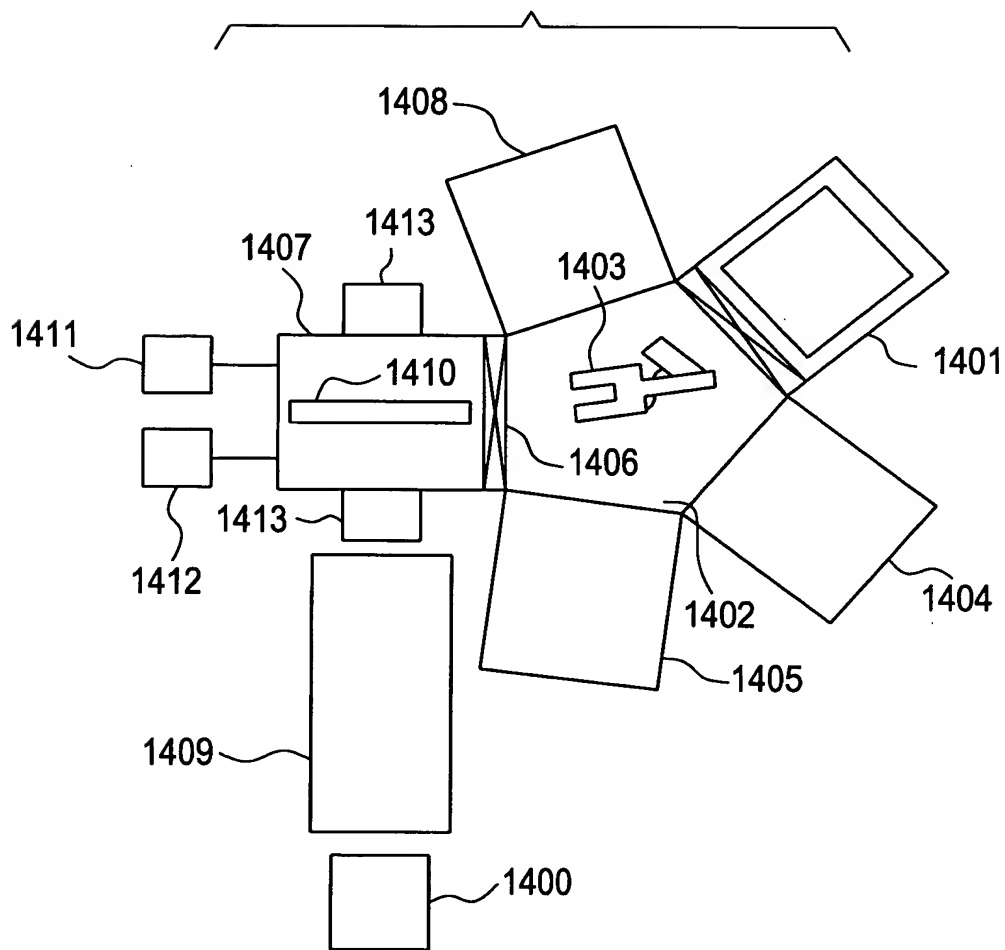
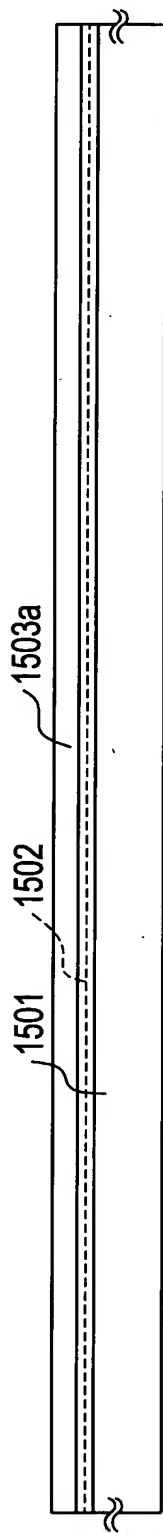


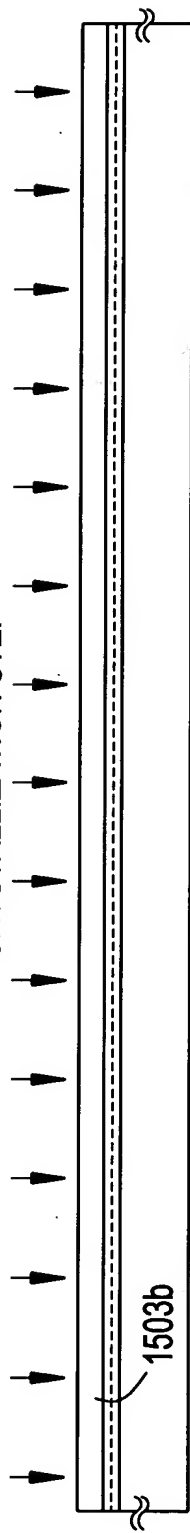
FIG. 14



**FIG. 15A**  
STEP OF FORMING AMORPHOUS SEMICONDUCTOR FILM

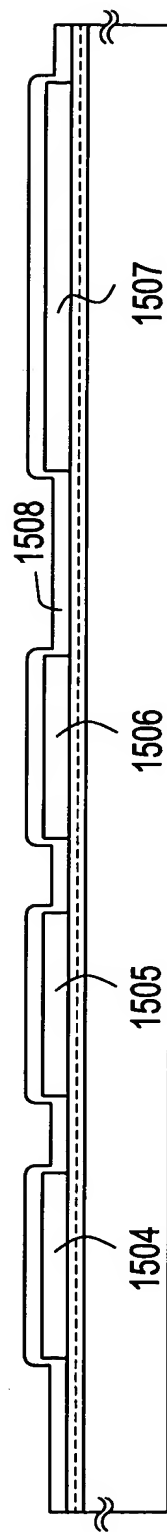


**FIG. 15B**  
CRYSTALLIZATION STEP

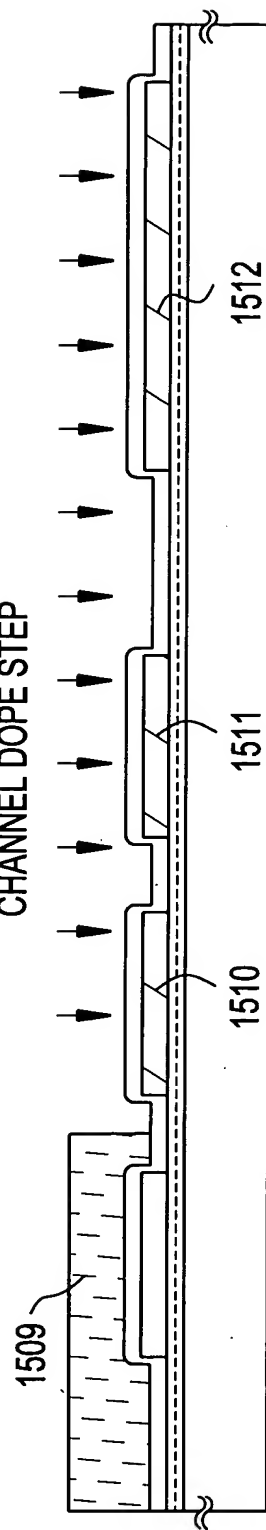


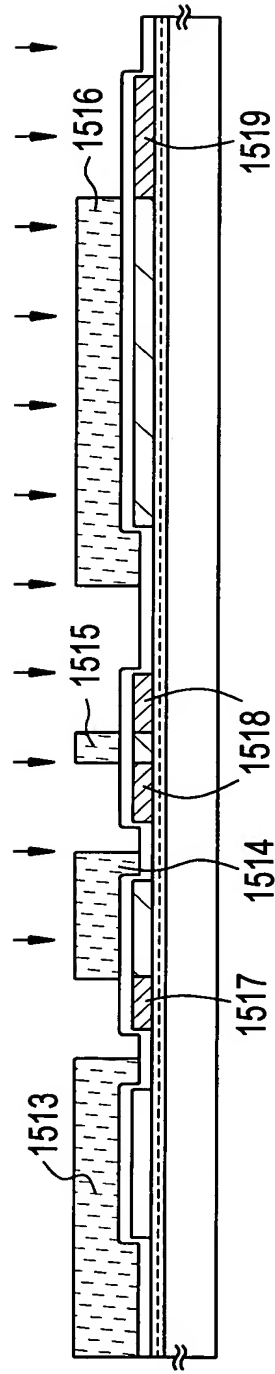
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**FIG. 15C**  
STEP OF FORMING MASK LAYER

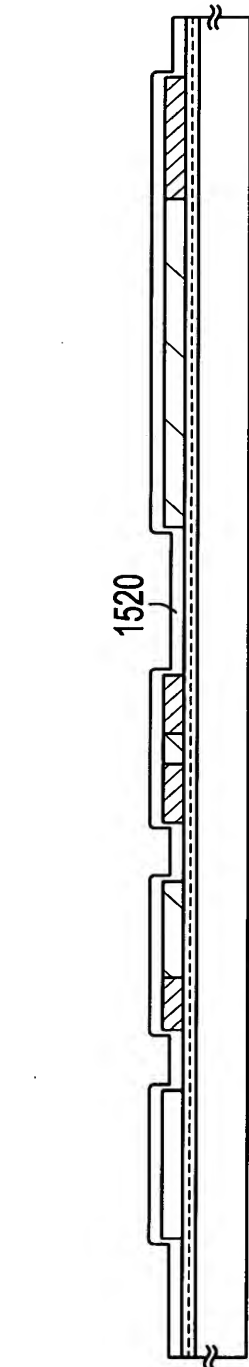


**FIG. 15D**  
CHANNEL DOPE STEP

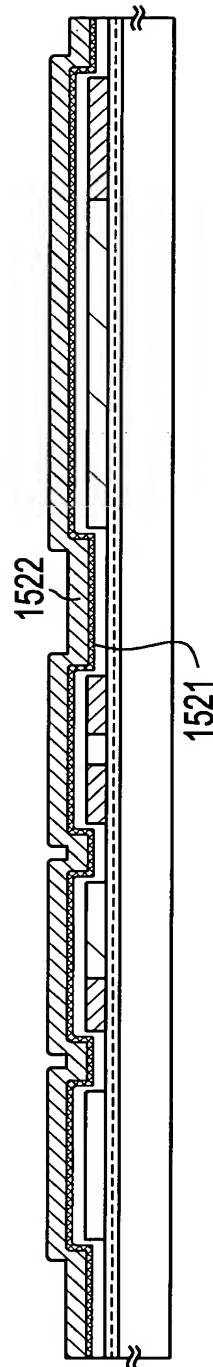




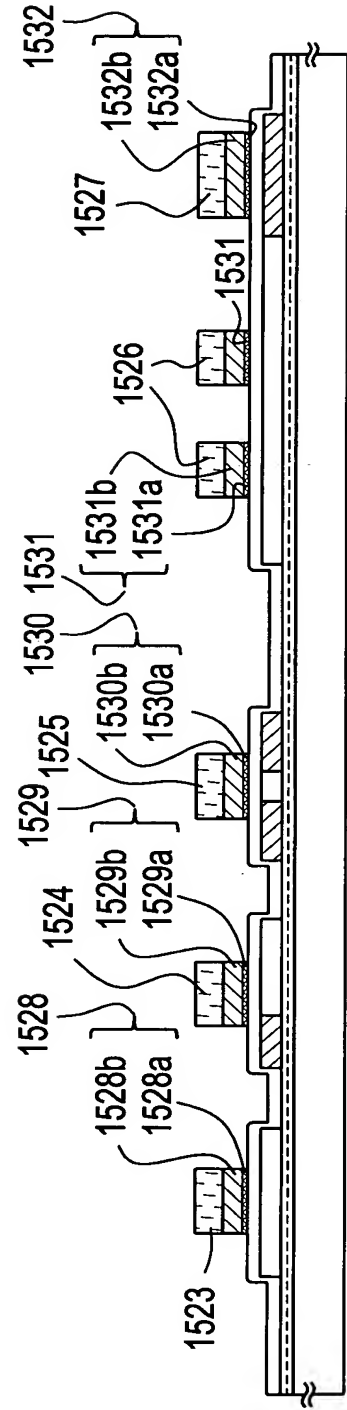
**FIG. 16A**  
n-DOPE STEP



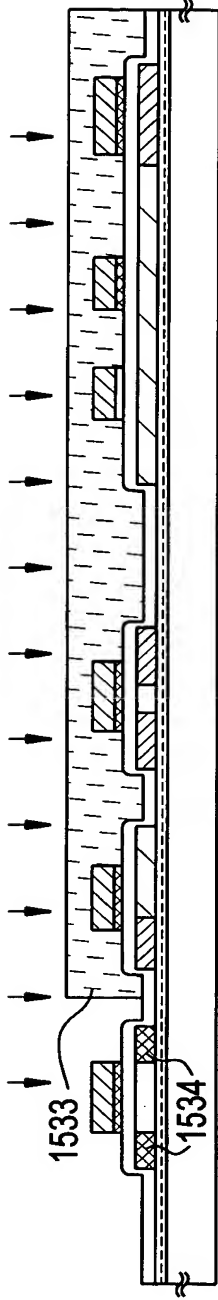
**FIG. 16B**  
STEP OF REMOVING  
FIRST MASK LAYER/  
LASER ACTIVATION STEP/  
STEP OF FORMING  
GATE INSULATING FILM



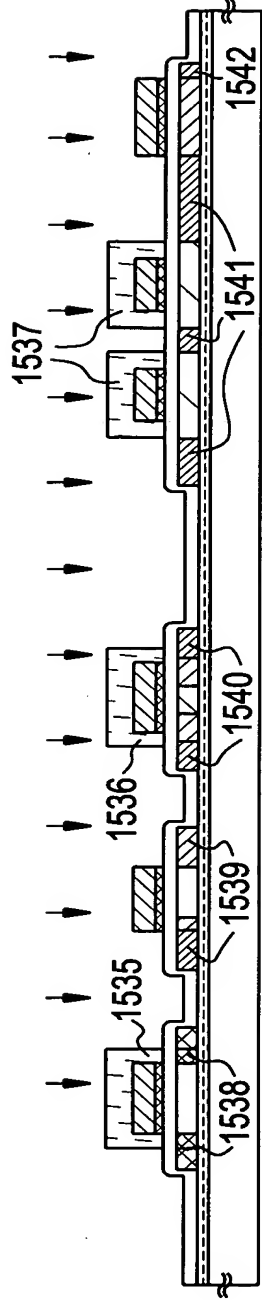
**FIG. 16C**  
STEP OF FORMING  
FIRST CONDUCTIVE  
LAYER



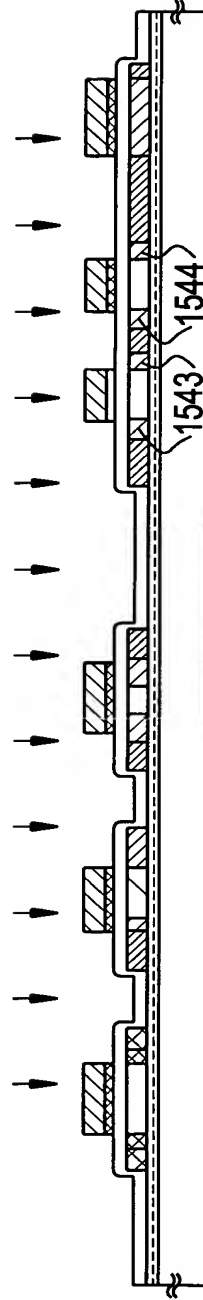
**FIG. 16D**  
STEP OF FORMING  
GATE ELECTRODE



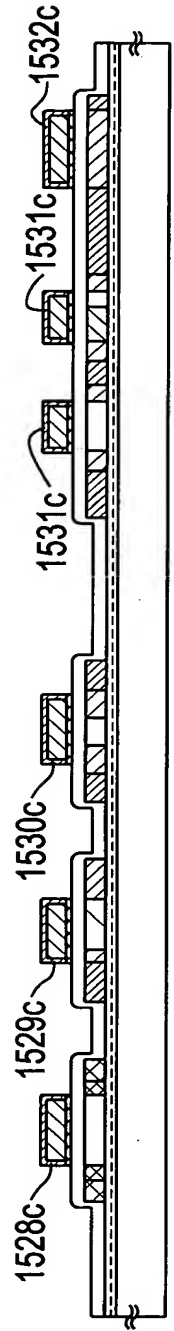
**FIG. 17A**  
P<sup>++</sup> DOPE STEP



**FIG. 17B**  
n<sup>+</sup> DOPE STEP



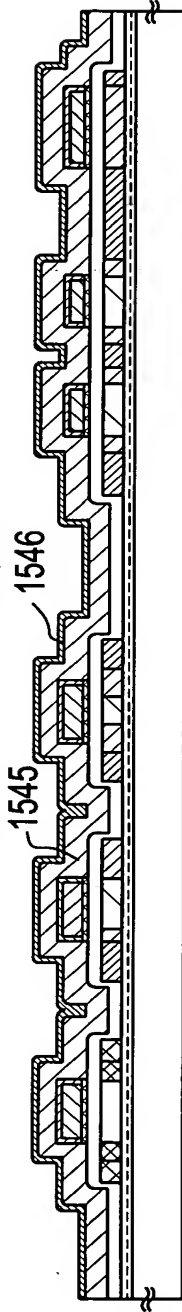
**FIG. 17C**  
n<sup>-</sup> DOPE STEP



**FIG. 18D**  
ACTIVATION STEP/  
INTRUDING STEP/  
HYDROGENATING STEP

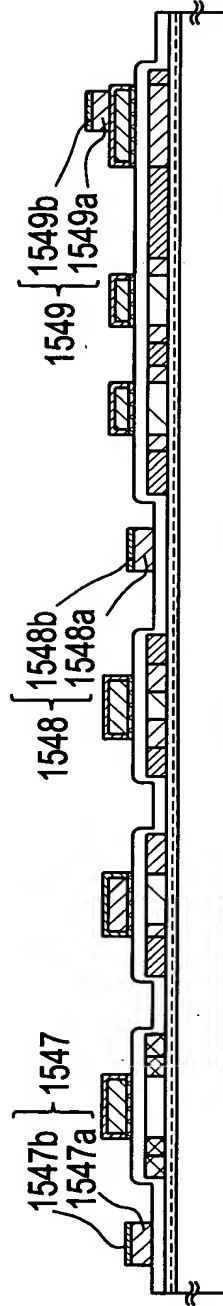
# FIG. 18A

STEP OF FORMING SECOND CONDUCTIVE FILM



# FIG. 18B

FORMATION OF GATE WIRING



# FIG. 18C

STEP OF FORMING INTERLAYER INSULATING FILM/ STEP OF FORMING CONTACT HOLE/  
STEP OF FORMING WIRING/ STEP OF FORMING PASSIVATION FILM

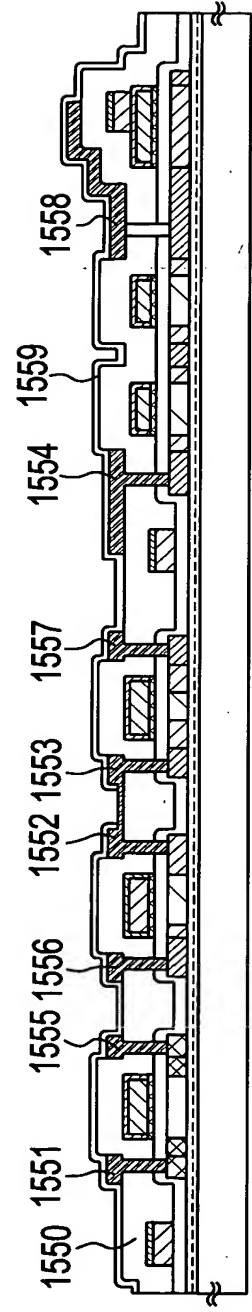




FIG. 19

STEP OF FORMING RESIN FILM/ STEP OF FORMING CONTACT HOLE/  
STEP OF FORMING PIXEL ELECTRODE

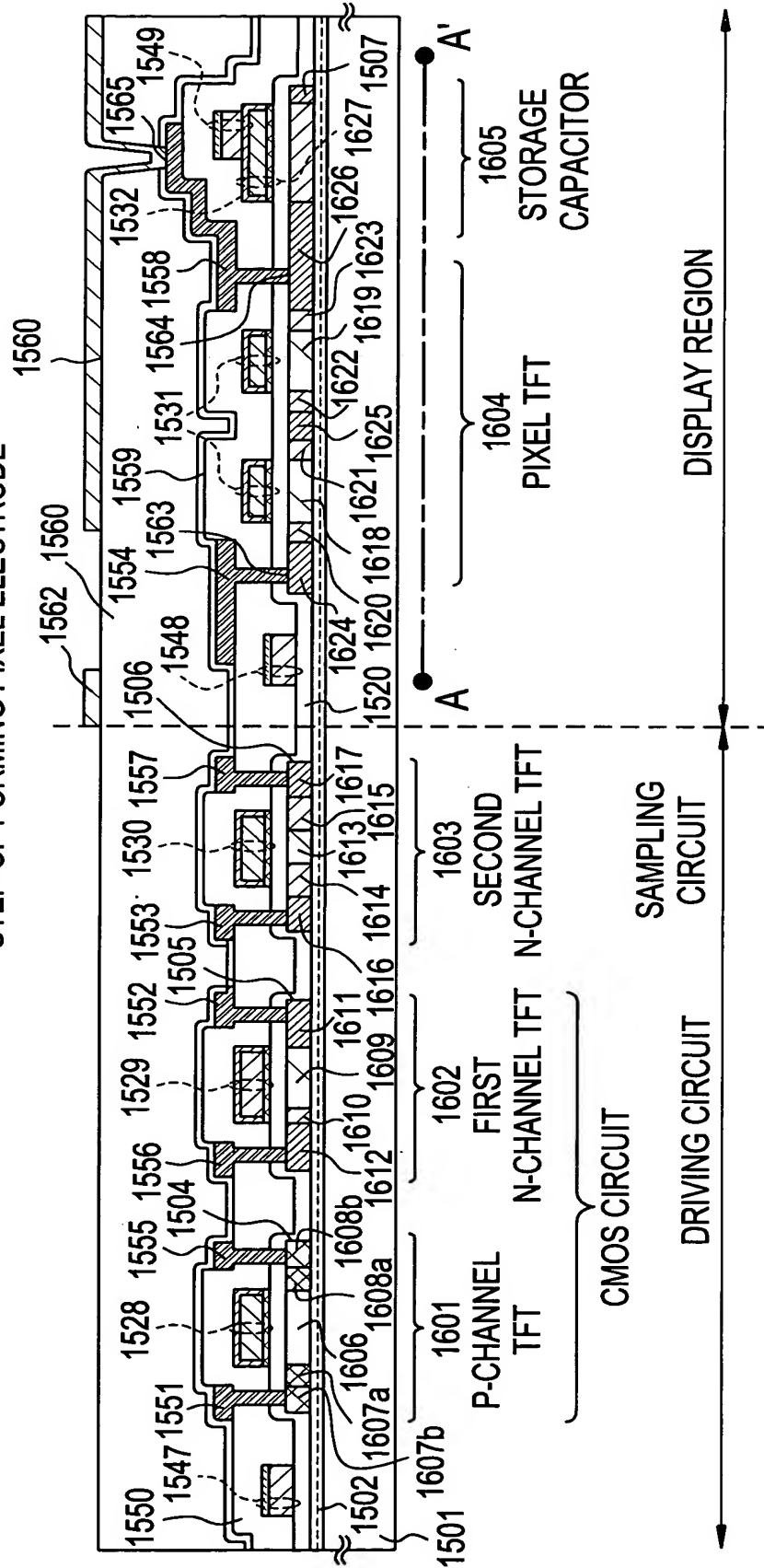


FIG. 20

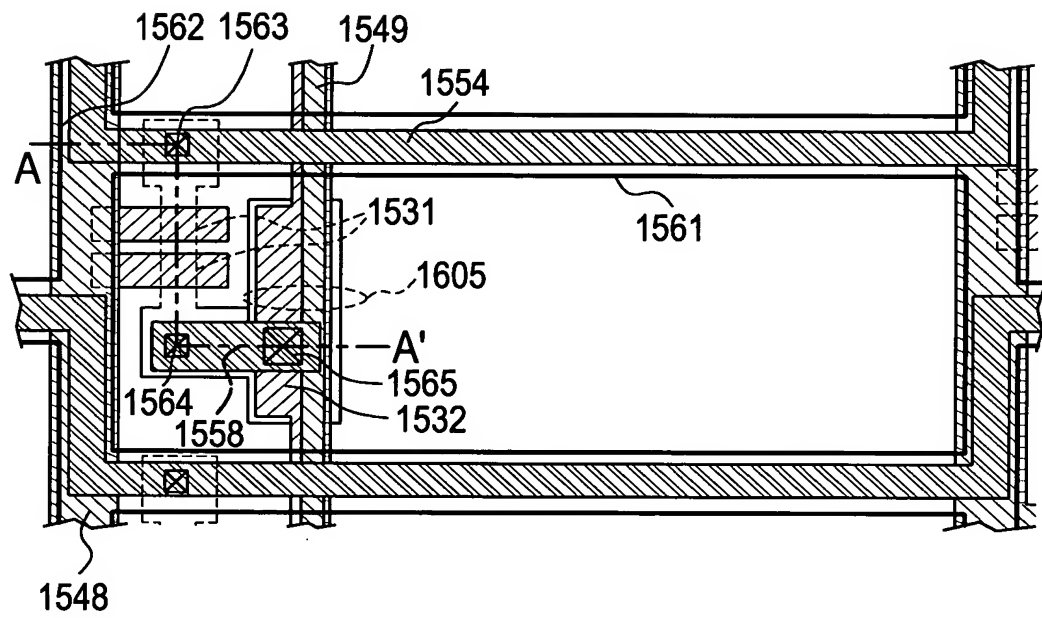
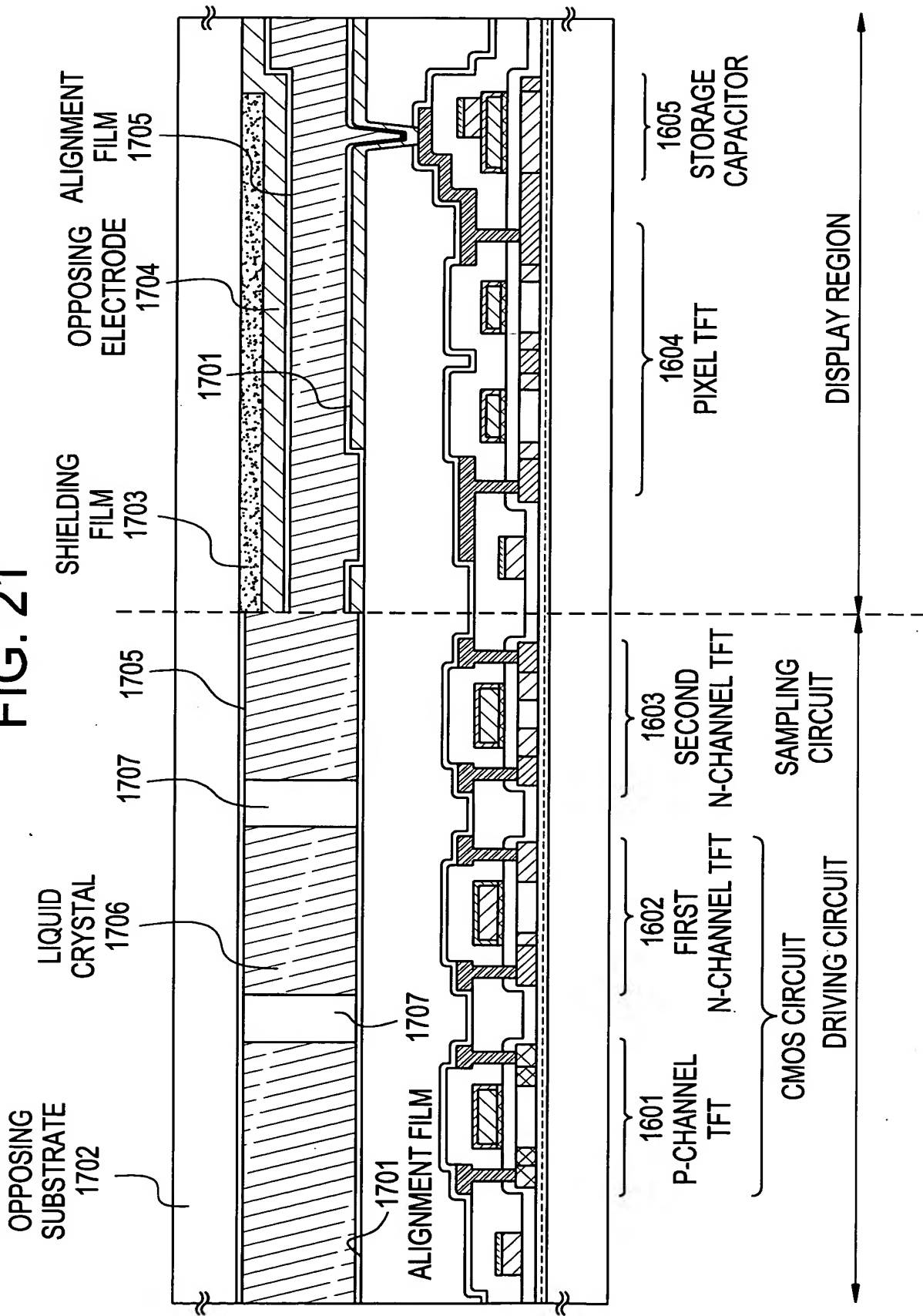
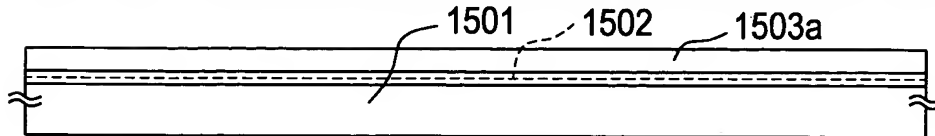


FIG. 21

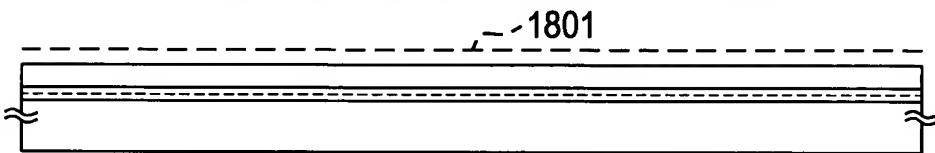


**FIG. 22A**

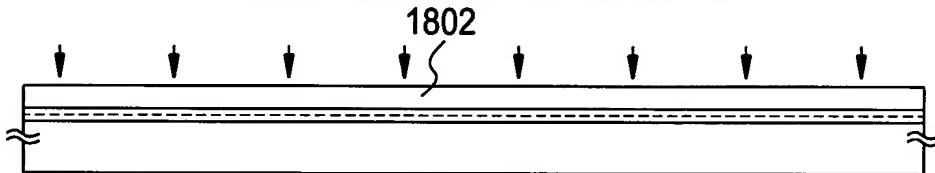
STEP OF FORMING AMORPHOUS SEMICONDUCTOR FILM

**FIG. 22B**

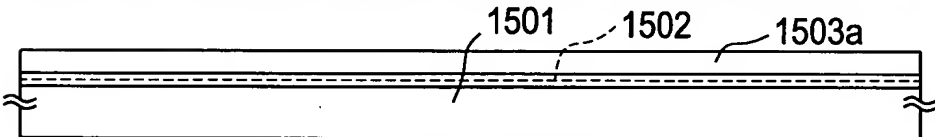
STEP OF ADDING CATALYST ELEMENT

**FIG. 22C**

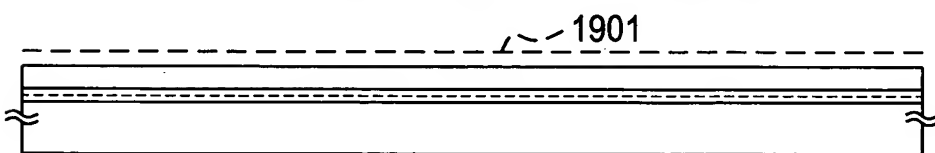
LASER CRYSTALLIZATION STEP

**FIG. 23A**

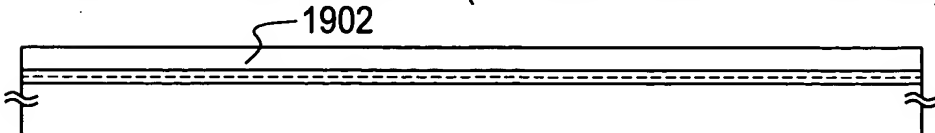
STEP OF FORMING AMORPHOUS SEMICONDUCTOR FILM

**FIG. 23B**

STEP OF ADDING CATALYST ELEMENT

**FIG. 23C**

CRYSTALLIZATION STEP (THERMAL CRYSTALLIZATION)

**FIG. 23D**

LASER ANNEAL STEP

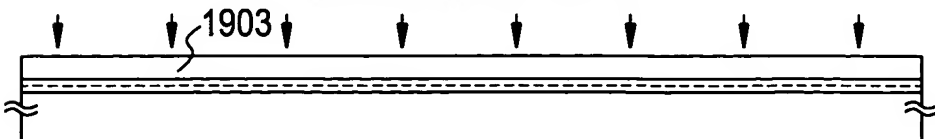


FIG. 24

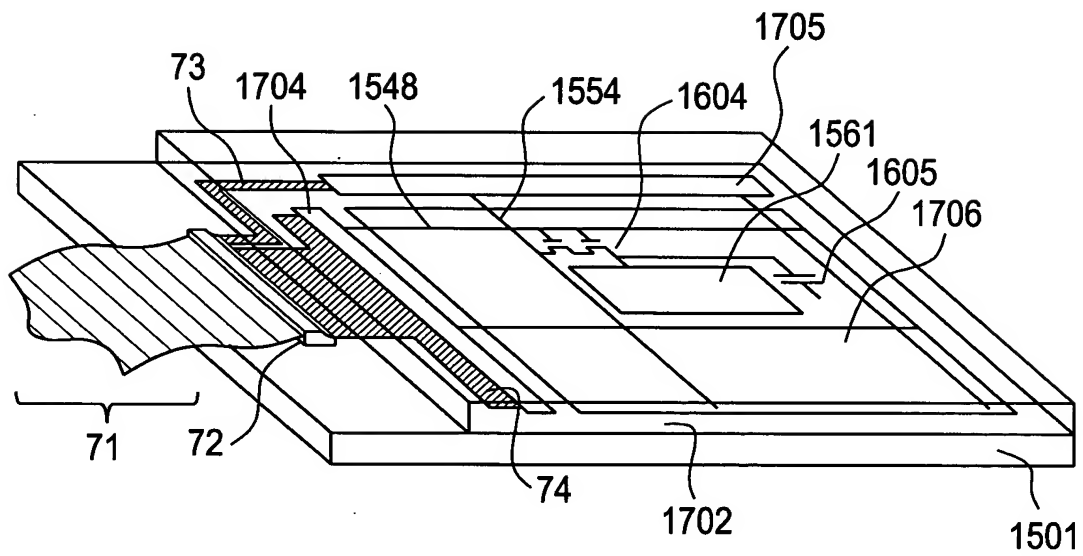


FIG. 25A

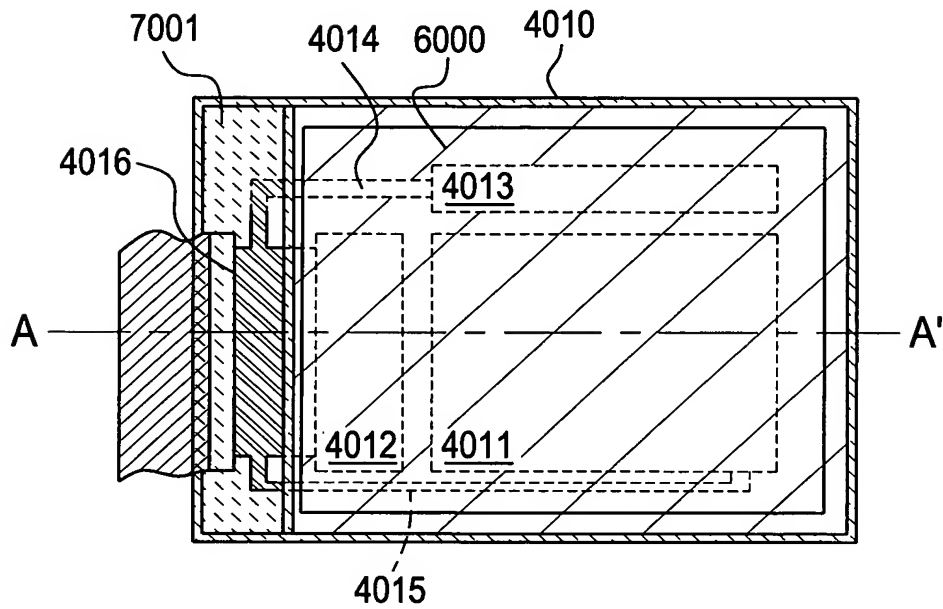


FIG. 25B

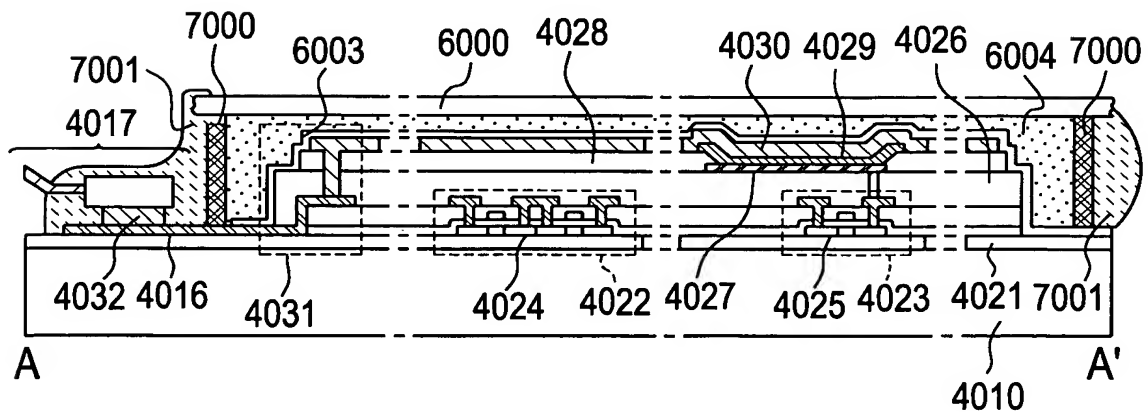


FIG. 26A

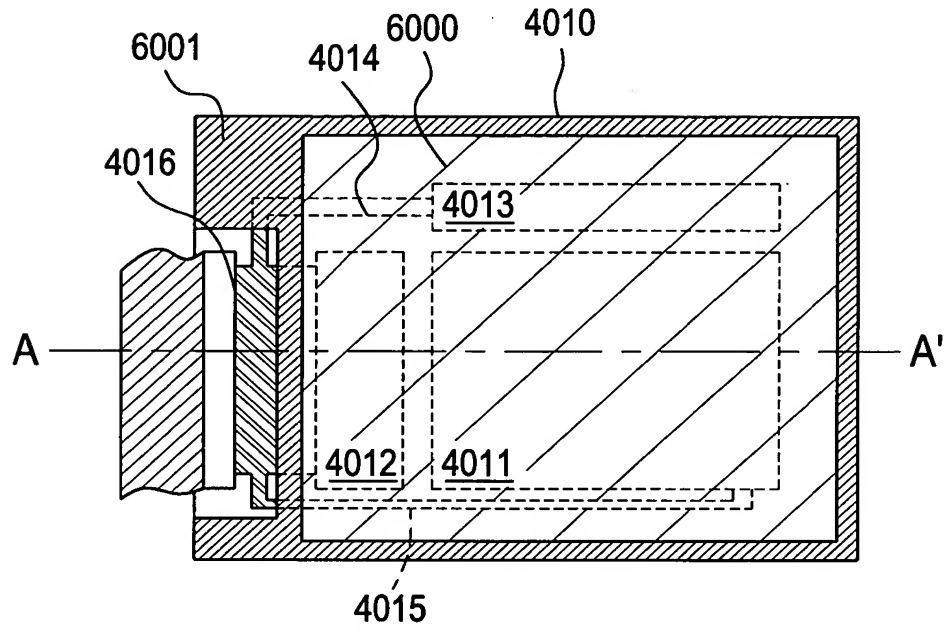


FIG. 26B

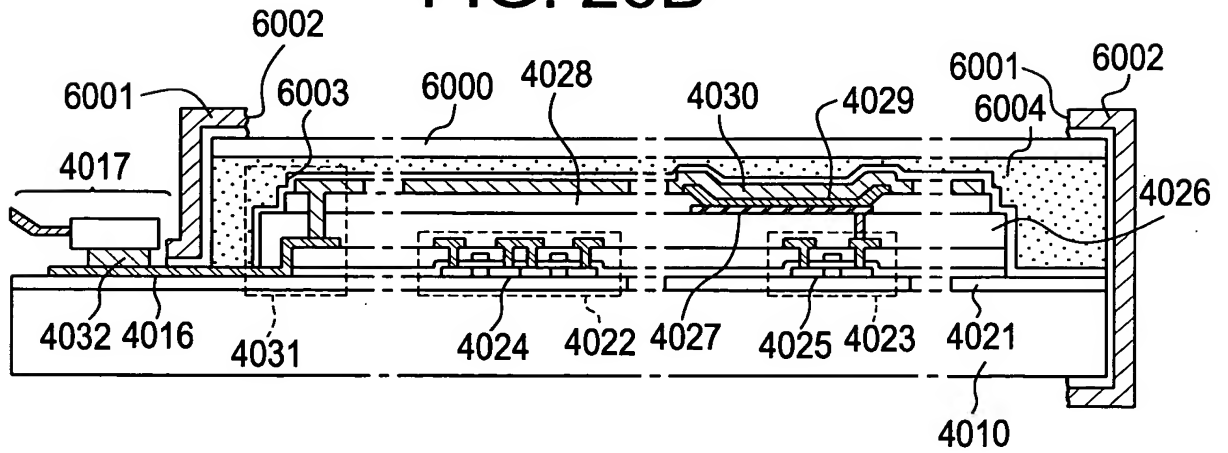


FIG. 27

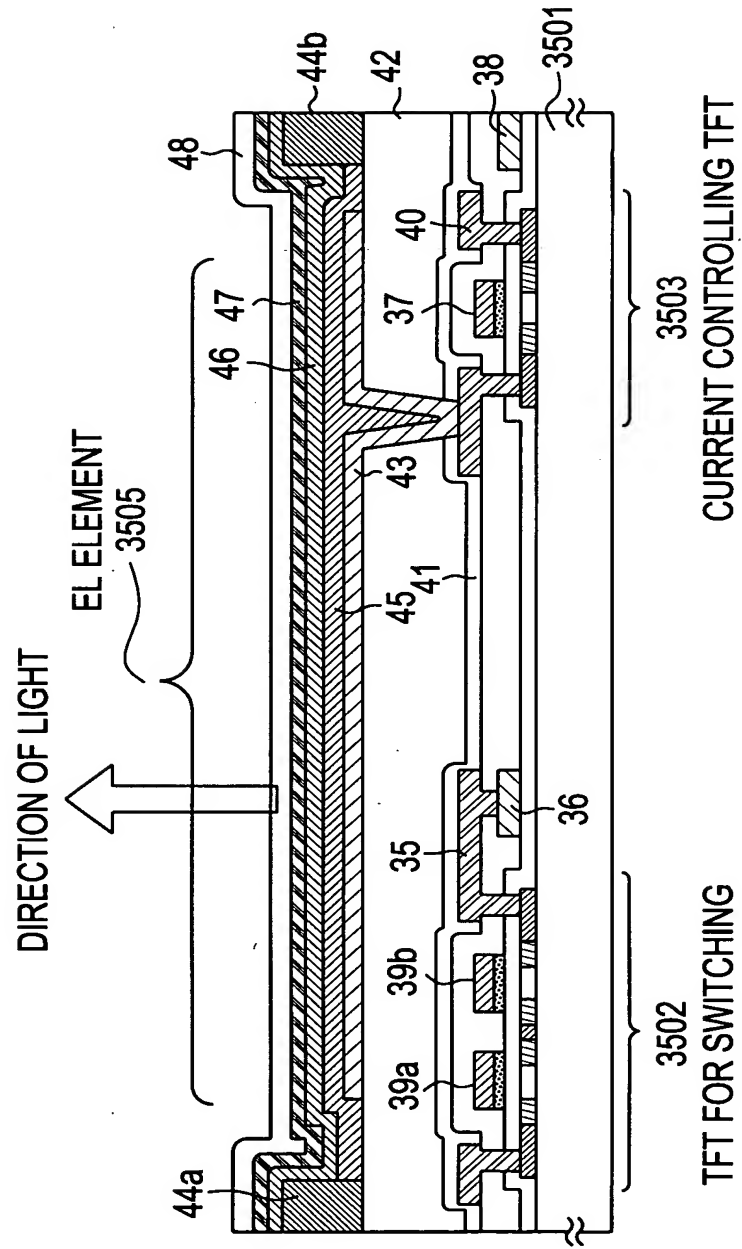




FIG. 28A

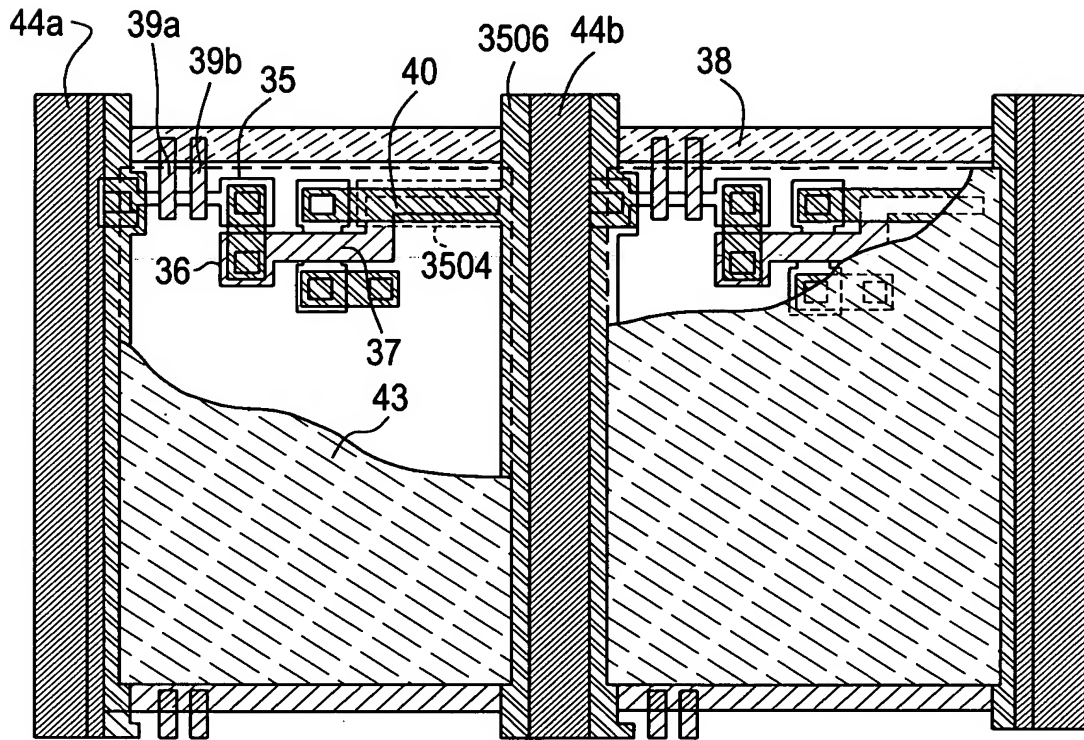


FIG. 28B

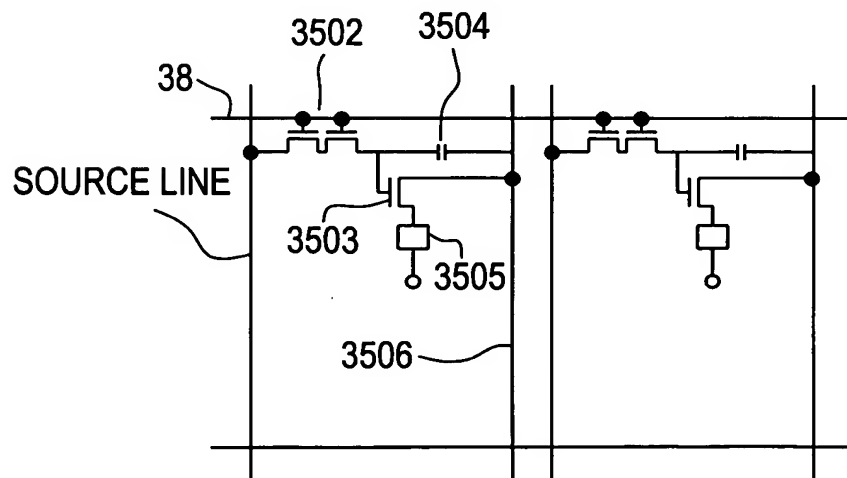


FIG. 29

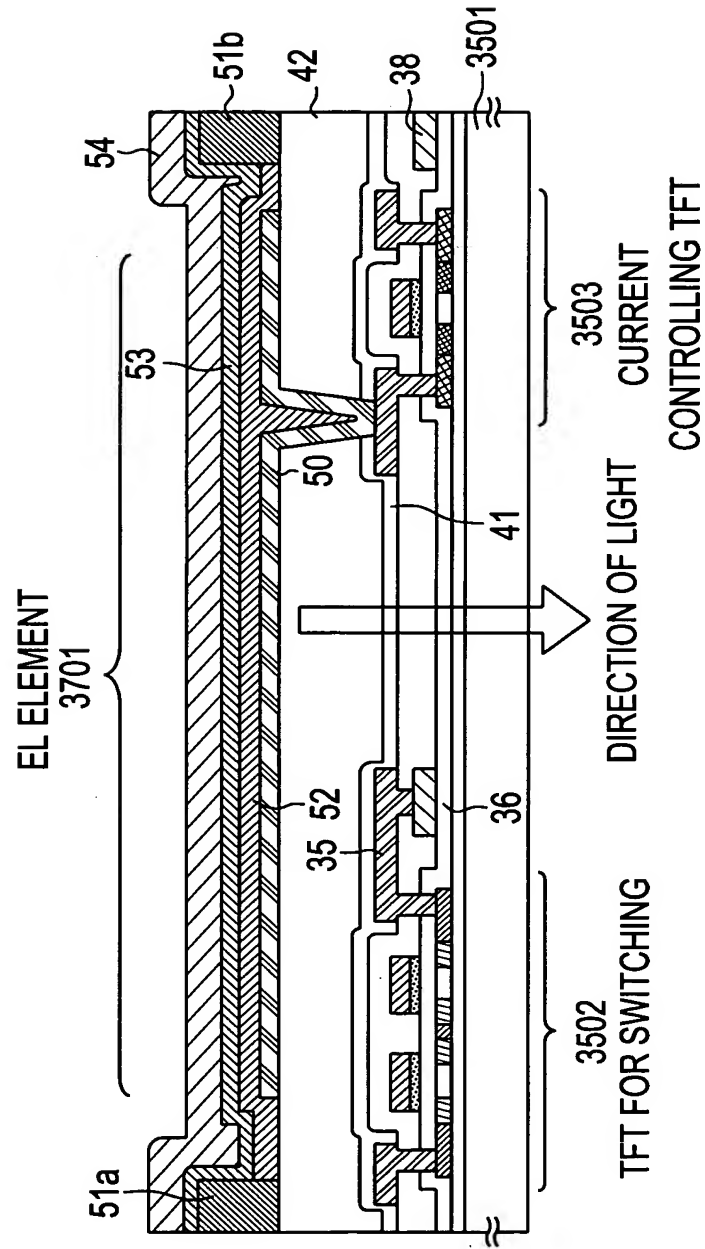


FIG. 30A

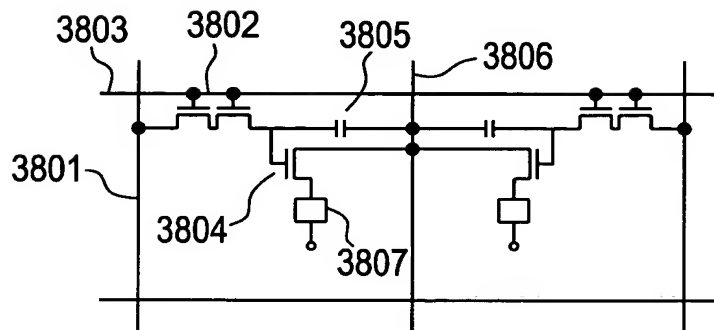


FIG. 30B

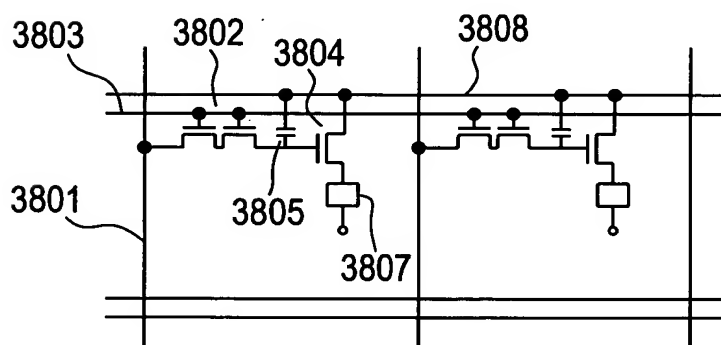


FIG. 30C

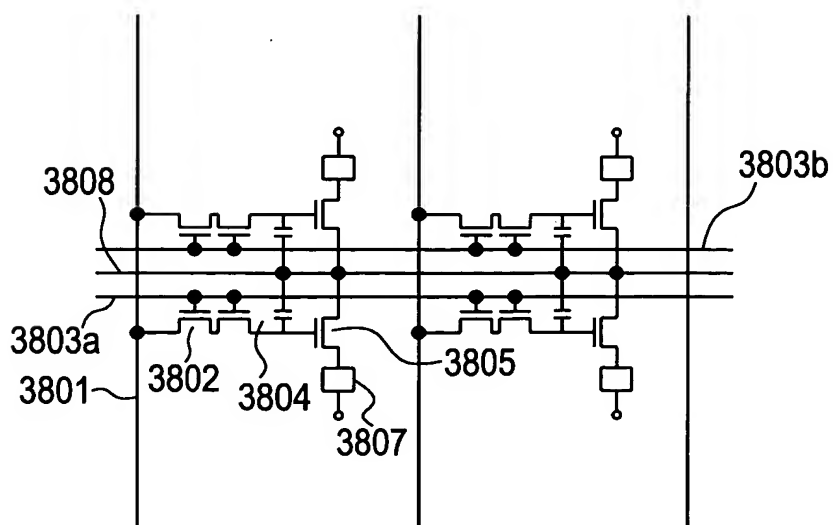


FIG. 31A

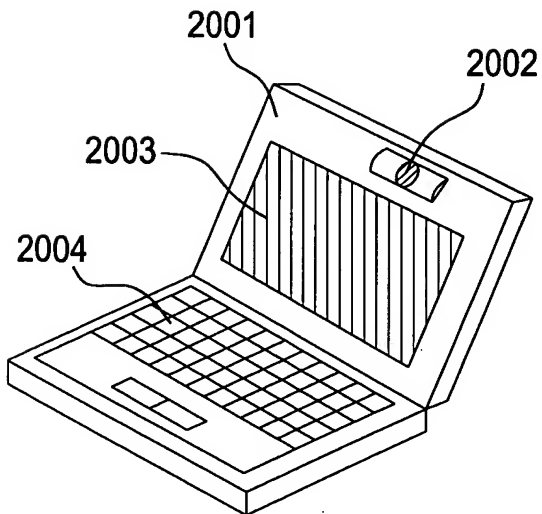


FIG. 31B

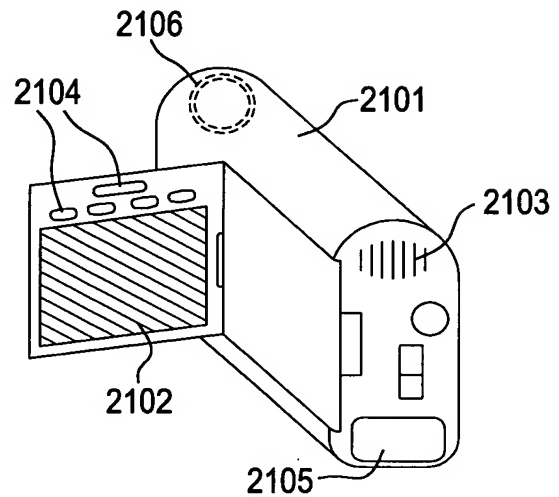


FIG. 31C

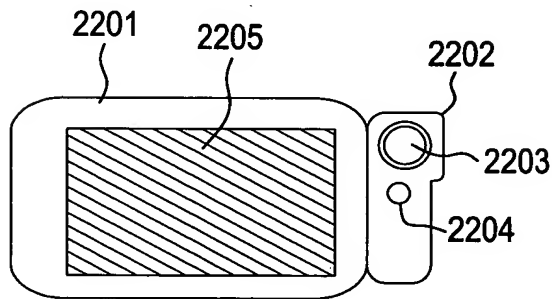


FIG. 31D

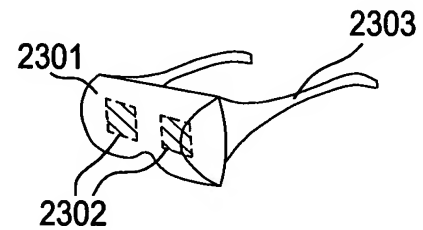


FIG. 31E

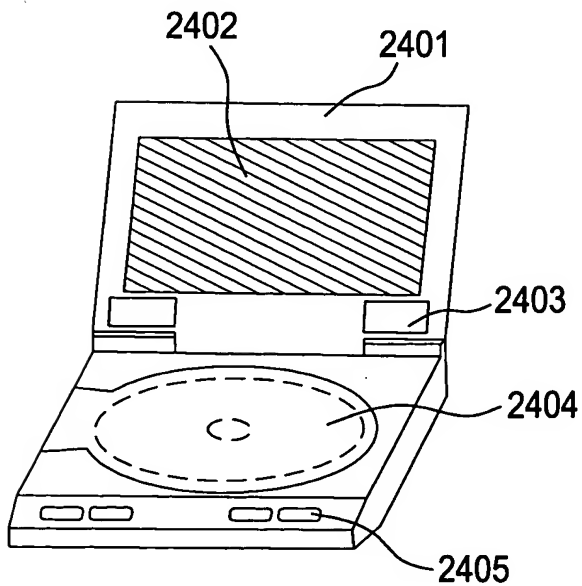
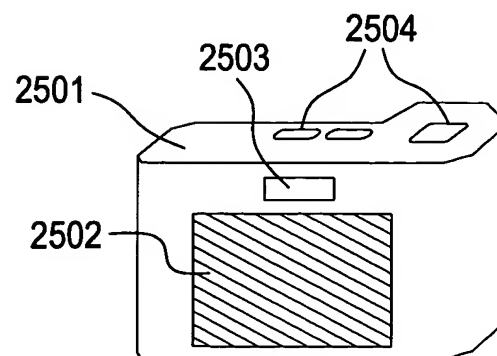
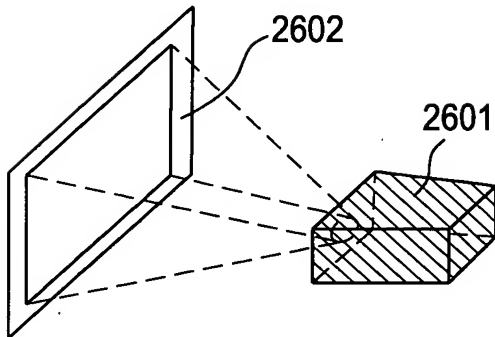
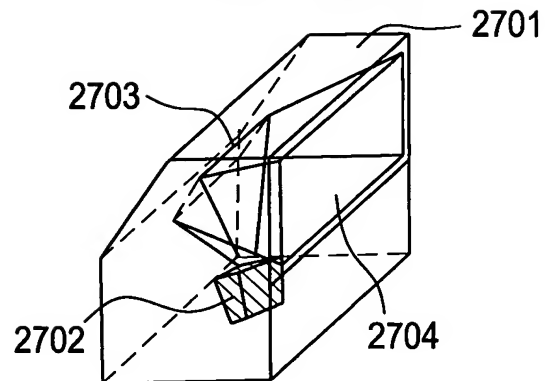
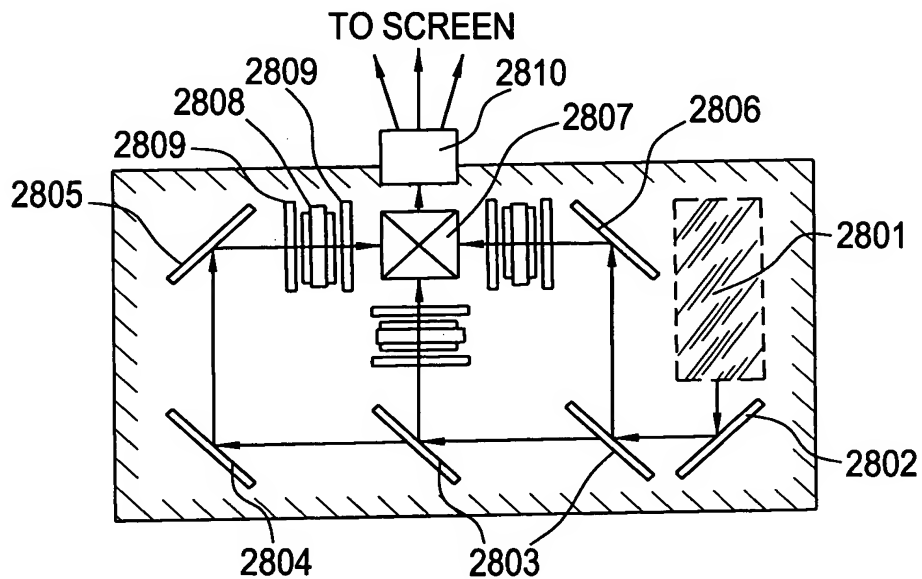


FIG. 31F



**FIG. 32A****FIG. 32B**

**FIG. 32C**  
PROJECTION UNIT  
(THREE PLATE SYSTEM)



**FIG. 32D**  
LIGHT SOURCE OPTICAL SYSTEM

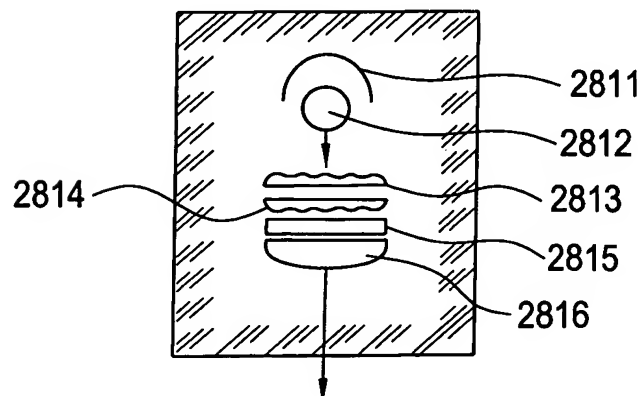


FIG. 33A

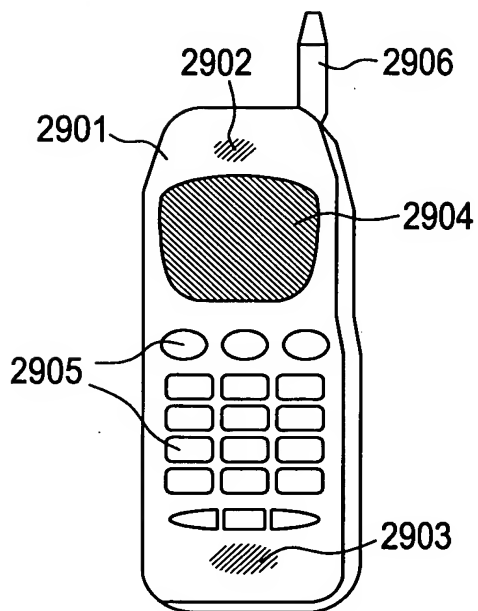


FIG. 33B

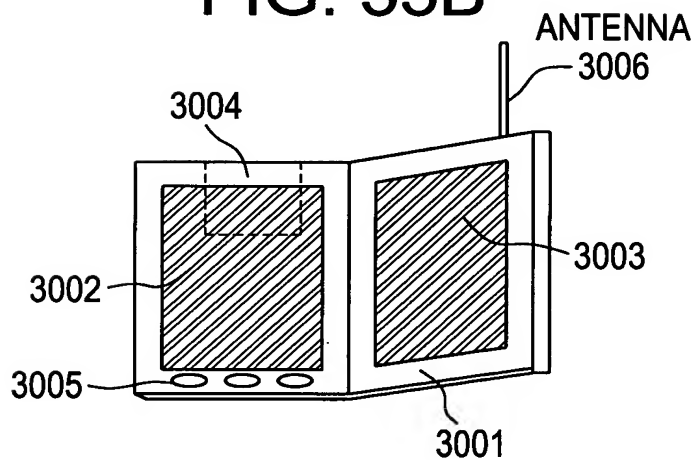
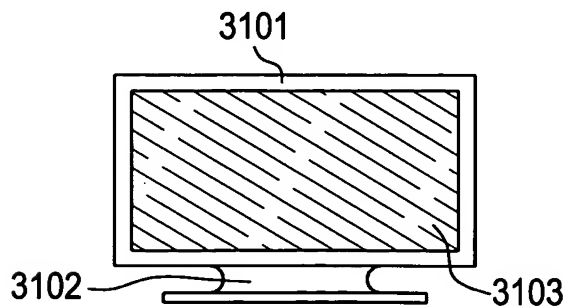


FIG. 33C



**FIG. 34**

ABSORPTION RATIO TO 55nm-THICK  
NON-SINGLE CRYSTAL SILICON FILM

